

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	DAE WON KIM	07/19/2021
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	THINKWARE CORPORATION	
<b>Street Address:</b>	FL. 9, A-DONG, 240, PANGYOYEOK-RO, BUNDANG-GU	
<b>City:</b>	SEONGNAM-SI, GYEONGGI-DO	
<b>State/Country:</b>	KOREA, REPUBLIC OF	
<b>Postal Code:</b>	13493	
<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	Application Number:	18212837
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Email:</b>	patentmail@whda.com	
<b>Correspondent Name:</b>	WHDA, LLP	
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<b>ATTORNEY DOCKET NUMBER:</b>	P230686US00	
<b>NAME OF SUBMITTER:</b>	SUNG-HOON KIM	
<b>SIGNATURE:</b>	/Sung-Hoon Kim/	
<b>DATE SIGNED:</b>	06/22/2023	
<b>Total Attachments: 2</b>		
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source=P230686US00_Assignment_06-22-2023#page2.tif		

ASSIGNMENT

I,

**Dae Won KIM** of FL. 9, A-DONG, 240, PANGYOYEOK-RO, BUNDANG-GU,  
SEONGNAM-SI, GYEONGGI-DO, REPUBLIC OF KOREA, 13493,

having invented certain inventions and improvements in **ELECTRONIC DEVICE AND METHOD FOR DETERMINING LIFESPAN AND FAILURE OF NONVOLATILE MEMORY STORAGE DEVICE**, and having executed an application for Letters Patent of the United States of America describing the same and based thereon (U.S. Patent Application Serial No. \_\_\_\_\_, filed \_\_\_\_\_), for good and valuable consideration, the receipt of which is hereby acknowledged from **THINKWARE CORPORATION**, a corporation, having its principal place of business at FL. 9, A-DONG, 240, PANGYOYEOK-RO, BUNDANG-GU, SEONGNAM-SI, GYEONGGI-DO, REPUBLIC OF KOREA, 13493, (hereinafter called the Assignee), do hereby sell, assign and transfer unto the Assignee, its successors, and assigns my entire right, title, and interest, in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto, in and to and under said application and the inventions and any of them therein set forth and described, and any and all patents and like rights of exclusion (including extensions thereof) of any country which may be granted on or for said inventions or any of them or any part thereof or on said application or any divisional, continuing, reissue, or other patent application based thereon;

And for the same consideration I do also hereby sell, assign, and transfer unto the Assignee, its successors, and assigns all my rights under the International Convention for the Protection of Industrial Property and all other treaties of like purpose in respect of said inventions and any of them and all parts thereof and said application, and I do hereby authorize the Assignee, its successors, and assigns to apply in my name or its or their own name or names for patents and like rights of exclusion on or for said inventions or any of them or any part thereof in all countries claiming if it or they so desire the priority of the filing date of said application under the provisions of said Convention or any such other treaty;

And for the same consideration, I do hereby agree for myself and for my heirs, executors, and administrators, promptly upon request of the Assignee, its successors, or assigns, to execute and deliver without further compensation any power of attorney, assignment, original, divisional, continuing, reissue or other application or applications for patent or patents or like rights of exclusion of any country, or other lawful documents and any further assurances that may be deemed necessary or desirable by the Assignee, its successors, or assigns fully to secure to it or them said right, title, and interest as aforesaid in and to said inventions and any of them and all parts thereof and in and to and under said several patents and like rights of exclusion (including extensions thereof) or any of them, all, however, at the expense of the Assignee, its successors, or assigns;

And I do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and the corresponding Officer of each country foreign thereto to issue to the Assignee, its successors, or assigns, any and all patents and like rights of exclusion

which may be granted in any country upon said United States application or other applications or any of them or on or for said inventions or any of them or any part thereof; and I do hereby covenant for myself and my legal representatives and agree with the Assignee, its successors, and assigns that I have granted no right or license to make, use, or sell said inventions or any of them or any part thereof to anyone except the Assignee, that prior to the execution of this deed my right, title, and interest in and to said inventions or any of them or any part thereof has not been otherwise encumbered by us, and that I have not executed and will not execute any instrument in conflict herewith.

IN WITNESS WHEREOF, I/we hereunto set my hand and seal on the day and year hereinafter noted.

July 19, 2021  
Date

*Dae won Kim*  
Dae Won KIM